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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Celli et al.

Art Unit: 1765

Serial No.: 09/599,718

Examiner: Brown, C.

Filing Date: 06/22/00

Docket No.: TI-29276

Title: PROCESS FLOW FOR DUAL DAMASCENE INTERCONNECT
STRUCTURES

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NAME OF INVENTOR(S): Celli TITLE OF INVENTION: Process Flow for Dual Damascene Interconnect <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%;">TI FILE NO.:</td> <td style="width: 50%;">DEPOSIT ACCT. NO.:</td> </tr> <tr> <td>TI-29276</td> <td>20-0668</td> </tr> </table> FAXED: 12/19/01 DUE: 12/21/01 ATTY/SECY: J.G.		TI FILE NO.:	DEPOSIT ACCT. NO.:	TI-29276	20-0668
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Request for Reconsideration under 37 CFR 1.115

Assistant Commissioner of Patents
Washington, DC 20231

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 08/21/01. They are respectfully submitted as a full and complete response to that Action.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-9 are pending in this case.

The Examiner rejected claims 1-9 under 35 U.S.C. §103(a) as being unpatentable over Jang et al. (U.S. Pat. No. 6,019,906) in view of Chen et al. (U.S. Pat. No. 6,211,061).